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ON Semiconductor®

FDC3535

P-Channel Power Trench $^{\circledR}$ MOSFET -80 V, -2.1 A, 183 m Ω

Features

- Max $r_{DS(on)}$ = 183 m Ω at V_{GS} = -10 V, I_D = -2.1 A
- Max $r_{DS(on)}$ = 233 m Ω at V_{GS} = -4.5 V, I_D = -1.9 A
- High performance trench technology for extremely low r_{DS(on)}
- High power and current handling capability in a widely used surface mount package
- Fast switching speed
- 100% UIL Tested
- RoHS Compliant

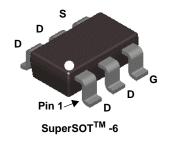


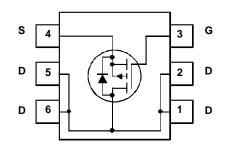
General Description

This P-Channel MOSFET is produced using ON Semiconductor's advanced Power Trench® process that has been optimized for $r_{DS(on)}$, switching performance and ruggedness.

Applications

- Load Switch
- Synchronous Rectifier





MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DS}	Drain to Source Voltage		-80	V
V _{GS}	Gate to Source Voltage		±20	V
	Drain Current -Continuous	(Note 1a)	-2.1	۸
ID	-Pulsed		-10	_ A
E _{AS}	Single Pulse Avalanche Energy	(Note 3)	37	mJ
	Power Dissipation	(Note 1a)	1.6	W
P_{D}	Power Dissipation	(Note 1b)	0.7	VV
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	30	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	78	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
.535	FDC3535	SSOT-6	7 "	8 mm	3000 units

Electrical Characteristics $T_J = 25 \, ^{\circ}\text{C}$ unless otherwise noted

Parameter

Off Char	acteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-80			V
$\Delta BV_{DSS} \over \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I_D = -250 μ A, referenced to 25 °C		-64		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -64 V, V _{GS} = 0 V			-1	μА
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

Test Conditions

Min

Тур

Max

Units

On Characteristics

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = -250 \mu A$	-1	-1.6	-3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = -250 μ A, referenced to 25 °C		5		mV/°C
		$V_{GS} = -10 \text{ V}, I_D = -2.1 \text{ A}$		147	183	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = -4.5 \text{ V}, I_D = -1.9 \text{ A}$		176	233	mΩ
, ,		$V_{GS} = -10 \text{ V}, I_D = -2.1 \text{ A}, T_J = 125 \text{ °C}$		246	307	
9 _{FS}	Forward Transconductance	V _{DD} = -10 V, I _D = -2.1 A		6.3		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 40 V V 0 V	659	880	pF
C _{oss}	Output Capacitance	$V_{DS} = -40 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$	49	65	pF
C _{rss}	Reverse Transfer Capacitance	I = I IVITIZ	24	40	pF
R_g	Gate Resistance		5.7		Ω

Switching Characteristics

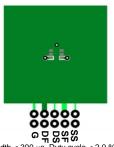
t _{d(on)}	Turn-On Delay Time		6.5	13	ns
t _r	Rise Time	$V_{DD} = -40 \text{ V}, I_{D} = -2.1 \text{ A},$	3.1	10	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = -10 \text{ V}, R_{GEN} = 6 \Omega$	23	38	ns
t _f	Fall Time		2.9	10	ns
0	Total Gate Charge	V _{GS} = 0 V to -10 V	14	20	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to } -4.5 \text{ V}$ $V_{DD} = -40 \text{ V}$	6.8	10	nC
Q_{gs}	Total Gate Charge	I _D = -2.1 A	1.6		nC
Q_{gd}	Gate to Drain "Miller" Charge		2.7		nC

Drain-Source Diode Characteristics

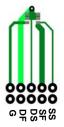
V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = -2.1 \text{ A}$	(Note 2)	-0.81	-1.3	V
t _{rr}	Reverse Recovery Time	-I _F = -2.1 A, di/dt = 100 A/μs		25	40	ns
Q_{rr}	Reverse Recovery Charge			23	38	nC

NOTES:

1. R_{BJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{BJC} is guaranteed by design while R_{BCA} is determined by the user's board design.



a. 78 °C/W when mounted on a 1 in² pad of 2 oz copper



b.175 °C/W when mounted on a minimum pad of 2 oz copper

- G D G G S 2. Pulse Test: Pulse Width < 300 μs, Duty cycle < 2.0 %.
- 3. Starting T $_J$ = 25 $^{o}C,\,L$ = 3 mH, I $_{AS}$ = -5 A, V $_{DD}$ = -80 V, V $_{GS}$ = -10 V.

Typical Characteristics T_J = 25 °C unless otherwise noted

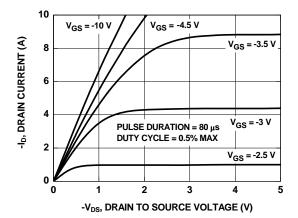


Figure 1. On-Region Characteristics

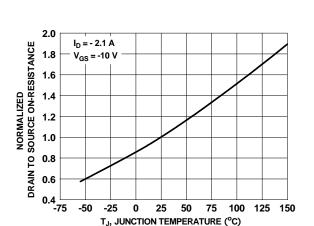


Figure 3. Normalized On-Resistance vs Junction Temperature

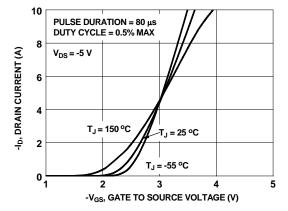


Figure 5. Transfer Characteristics

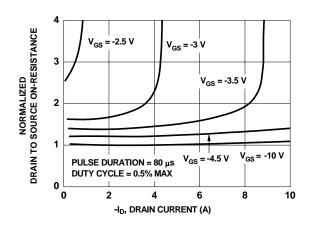


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

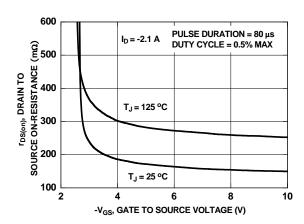


Figure 4. On-Resistance vs Gate to Source Voltage

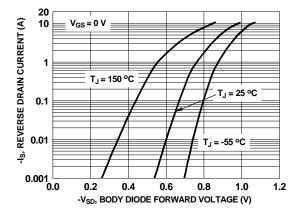


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted

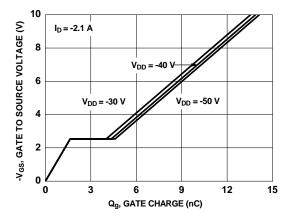


Figure 7. Gate Charge Characteristics

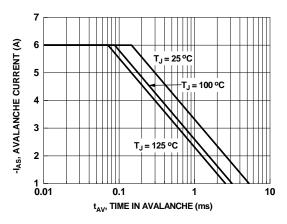


Figure 9. Unclamped Inductive Switching Capability

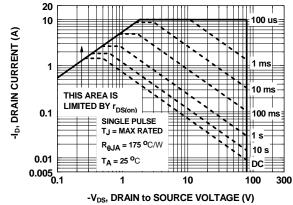


Figure 11. Forward Bias Safe
Operating Area

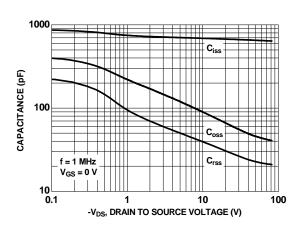


Figure 8. Capacitance vs Drain to Source Voltage

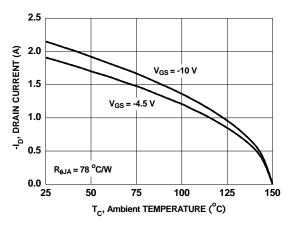


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

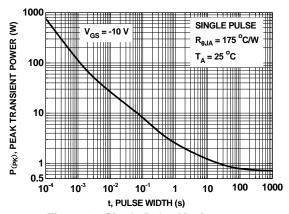


Figure 12. Single Pulse Maximum Power Dissipation



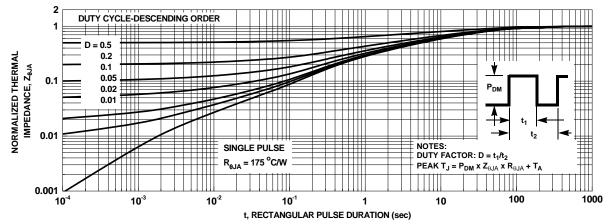


Figure 13. Junction-to-Ambient Transient Thermal Response Curve

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